CALL FOR PAPERS

International Conference on
Pacific Rim Laser Damage & Thin Film Physics and Applications

Conference: 19-22 May 2019, Qingdao, China
Website: pldtfpa2019.htcis.net
Abstracts Due: 20 February 2019

On behalf of the Conference Chairs and the Program Committee, we invite you to participate by submitting your abstract to the International Conference on Pacific Rim Laser Damage & Thin Film Physics and Applications (SPIE-PLD/TFPA 2019).

By bringing together the high-quality technical content, influential speakers worldwide, comprehensive topic categories, and latest technologies, SPIE-PLD/TFPA 2019 is to serve as a platform on exchanging information on recent advances and future trends for researchers and their peers, and to boost brand for the enterprises. We hope that this conference will contribute to the enhancement of understanding between attendees and facilitate closer collaborations among participating researchers.

We urge you to participate by submitting your abstracts, and to encourage your colleagues to do the same.

Hosts:

Organizers:

Technical Sponsor:
SPIE.
SPIE-PLD/TFPA 2019 features two meetings: The 8th Pacific Rim Laser Damage: Optical Materials for High Power Lasers Symposium (PLD 2019) and The 10th International Conference on Thin Film Physics and Applications (TFPA 2019).

**The 8th Pacific Rim Laser Damage (PLD 2019)**

**PLD 2019 Conference Chairs:**
- Jianda Shao
  Shanghai Institute of Optics and Fine Mechanics, CAS (China)
- Takahisa Jitsuno
  Osaka Univ. (Japan)
- Wolfgang Rudolph
  The Univ. of New Mexico (United States)

**Technical Program Committee**
- MJ Soileau, Univ. of Central Florida (United States)
- Efim A. Khazanov, Institute of Applied Physics (Russia)
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- Jean-Yves Natoli, Institute Fresnel (France)
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- Christopher J. Stolz, Lawrence Livermore National Lab. (United States)
- Koji Sugioka, RIKEN (Japan)
- Takunori Taira, Institute for Molecular Science (Japan)
- Mauro Tonelli, Univ. di Pisa (Italy)
- Zhouling Wu, ZC Optoelectronic Technologies Ltd. (China)
- Qiao Xu, China Academy of Engineering Physics (China)
- Ioan Dancus, Horia Hulubei National Institute of Physics and Nuclear Engineering (Romania)

PLD 2019 will address the field of laser damage and optical materials in the following areas:

**Session 1: Laser Damage of Optical Materials**
- High power laser damage, UV through IR
- Ultrafast through CW laser irradiation effects
- Laser ablation and laser machining
- High laser damage resistant coatings
- Defects, contamination, polishing, and surface damage
- Characterization techniques and measurement protocols
- Mechanisms, modeling, and simulations

**Session 2: Advanced Optical Materials**
- Nonlinear laser crystals
- Laser ceramics
- Optical glasses and fibers

**The 10th International Conference on Thin Film Physics and Applications (TFPA 2019)**

**TFPA 2019 Conference Chairs:**
- Junhao Chu
  Academician of Chinese Academy of Sciences, Shanghai Institute of Technical Physics, CAS (China) and East China Normal Univ. (China)
- Jianda Shao
  Shanghai Institute of Optics and Fine Mechanics, CAS (China)

**Technical Program Committee**
- Ruxin Li, Shanghai Institute of Optics and Fine Mechanics, CAS (China)
- Shining Zhu, Nanjing Univ. (China)
- Min Gu, RMIT Univ. (Australia)
- Andrea C. Ferrari, Univ. of Cambridge (United Kingdom)
- Sam Zhang, Nanyang Technological Univ. (Singapore)
- Frank Placido, Univ. of the West of Scotland (United Kingdom)
- Alexander V. Tikhonravov, Lomonosov Moscow State Univ. (Russia)
- Angela M. Piegarì, Italian National Agency for New Technologies, Energy and Sustainable Economic Development (ENEA), Casaccia Research Centre (Italy)
- Chang Kwon Hwangbo, Inha Univ. (Korea)
- Enam A. Chowdhury, The Ohio State Univ. (United States)
- Long Zhang, Shanghai Institute of Optics and Fine Mechanics, CAS (China)

TFPA 2019 will address the field of thin film physics and applications in the following areas:
- Physics of thin films
- Thin film materials
- Technology of thin films
- Application of thin films

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